mail

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



INTERCONNECTS

SERIES 834 & 835 • 2,54 GRID OFP® PASS-THROUGH SOCKETS Ø0,76 & 0,64 PINS · SINGLE AND DOUBLE ROW STRIPS

- 834/835 Series Pass-Through Sockets have a low 3,30 profile and will accept Ø 0,76 round pin, as well as industry standard 0,64 square pin headers.
- They are typically used to interconnect two or more parallel circuit boards.
- Sockets are designed for hand, wave or reflow* soldering. The high temperature insulator is compatible with all solder processes.
- Unique ORGANIC FIBRE PLUG® barriers prevent solder, paste or flux from contaminating the internal spring contacts. After soldering, the OFP[®] barriers are pushed out of the socket when the mating header is inserted.
- Mill-Max sockets use a receptacle consisting of a precision-machined brass sleeve with a press-fit beryllium copper "multi-finger" spring contact.
- Recommended mounting holes are Ø1,17 ±0,08 PTH (1,2 mm drilled prior to plating).

*Intrusive reflow (also called "pin-in-paste") is a technique of using conventional through-hole components in a reflow soldering process. The pass-through socket is placed into plated through-holes in the circuit board (solder paste has previously been screen printed on pads adjacent to the holes) and the board is reflowed in the same pass as other SMT components. Solder will fill the plated through-holes and achieve solder joints as reliable as wave soldering. The OFP[®] barrier prevents solder paste from being picked up inside the contact during assembly.





See Below

93

5.08um Sn/Pb

0,76µm Au

& Enviromental Data,

See page 264



SPECIFY PLATING CODE XX=

Sleeve (Pin)

Contact (Clip)

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